

Listing of the Claims:

The following is a complete listing of all the claims in the application, with an indication of the status of each:

1. (Currently amended) A method for gluing microcomponents (18) to a substrate (1) in the production of microsystem components, comprising the following steps:

- [-] applying a reactive or nonreactive hotmelt adhesive (5) to at least one microcomponent the microcomponent (18) and/or the substrate (1);
- [-] heating the hotmelt adhesive (5), and
- [-] applying the at least one microcomponent (18) to the substrate (1), the hotmelt adhesive (5) being on the contact areas between the at least one microcomponent (18) and the substrate (1), characterized by wherein said applying step includes
- [-] areal application of pulverulent hotmelt adhesive (5) to the a surface of the substrate (1) or the at least one microcomponent (18),
- [-] incipient melting of selected bond sites (7) by local heating by means of irradiation of the selected bondsites through a focusable heat source (11) of the a powder layer;
- [-] removal of the powder layer not incipiently melted; and
- [-] adhesion of the at least one microcomponent (18) to the substrate (1).

2. (Currently amended) The method of claim 1, wherein said characterized in that the heating takes place selectively with a focusing heat source (11), in particular by means of laser.

3. (Currently amended) The method of claim 1 wherein or 2, characterized in that the hotmelt adhesive (5) is applied as granules.

4. (Currently amended) The method of claim 1 wherein one of the preceding claims, characterized in that the incipient melting takes place with a laser.

5. (Currently amended) A The method of claim 1 further comprising the step of

one of the preceding claims, characterized by immersing a heated substrate (1) or microcomponent (18) in pulverulent hotmelt adhesive to apply the adhesive (5) at the immersed areas.

6. (Currently amended) The method of claim 1 wherein said applying step includes one of the preceding claims, characterized by application of pulverulent hotmelt adhesive through a contoured screen (13) to the substrate (1) or the at least one microcomponent (18).

7. (Currently amended) The method of claim 1 further comprising the step of one of the preceding claims, characterized by electrostatic charging of a surface and/or a pulverulent hotmelt adhesive (5) to support the areal or patterned application of adhesive.

8. (Currently amended) The method of claim 1 further comprising the step of one of the preceding claims, characterized by immersion of a heated patterned surface of the substrate (1) or the at least one microcomponent (18) in pulverulent hotmelt adhesive to apply the adhesive (5) at the raised sites on the patterned surface.

9. (Currently amended) The method claim 1 further comprising the steps of one of the preceding claims, characterized by electrostatic charging of a roll (12), and wherein areal application of the pulverulent hotmelt adhesive is made to a the partly electrostatically charged surface of the roll (12) and

transfer of the transferring selected bondsites (7) from the roll (12) to the substrate (1) or the at least one microcomponent (18), and wherein brief heating of the surface is used to incipiently melt the adhesive (5).

10. (Currently amended) The method of claim 1 further comprising the step of one of the preceding claims, characterized by electrostatic charging of the selected bondsites, and wherein areal application of the pulverulent hotmelt adhesive is performed to a the partly electrostatically charged surface of the substrate (1) or the at least one microcomponent (18), and brief heating of the surface is performed to incipiently melt the adhesive (5) at the electrostatically charged bondsites (7).

11. (Currently amended) The method of claim 1, further comprising characterized by placement of a transfer sheet (15) with granular or pulverulent adhesive (5) attaching thereto, or of a layer produced from hotmelt adhesive, to the adherend surface of the at least one microcomponent (18) or substrate (1).

12. (Currently amended) The method of claim 11, further comprising the step of characterized by contouring of the transfer sheet (15) to select bondsites (7).

13. (Currently amended) The method of claim 11, characterized by application of the adhesive (5) to selected bondsites (7), when the transfer sheet (15) lies on the surface of at least one microcomponent (18) or substrate (1), by mechanically stamping the transfer sheet (15) onto the substrate (1) or the at least one microcomponent (18) or locally heating the transfer sheet (15).

14. (Currently amended) The method of claim 1 further comprising the step of one of the preceding claims, characterized by preheating of at least ~~the~~ surfaces to which adhesive (5) is applied.

15. (Currently amended) The method of claim 1 further comprising the step of one of the preceding claims, characterized by afterheating of the at least one microsystem component after adhering the at least one microcomponent (18) has been adhered to the substrate (1).

16. (Currently amended) The method of claim 14, wherein characterized in that the afterheating takes place selectively by means of focusing heat source (11) or globally.

17. (Currently amended) The method of claim 1 wherein one of the preceding claims, characterized in that the granules of the adhesives (5) have a diameter of less than 150 µm.

18. (Original) The method of claim 17, characterized in that the diameter of the granules is situated in the range from 0.5 to 150 µm.

19. (Currently amended) A microsystem component having at least one microcomponent (18) bonded to a substrate (1), characterized in that the adhesive bonding is performed by the method of ~~one of claims 1 to 18~~

applying a reactive or nonreactive hotmelt adhesive to at least one microcomponent and/or the substrate;

heating the hotmelt adhesive, and

applying the at least one microcomponent to the substrate, the hotmelt adhesive being on the contact areas between the at least one microcomponent and the substrate, wherein said applying step includes

areal application of pulverulent hotmelt adhesive to a surface of the substrate or the at least one microcomponent,

incipient melting of selected bond sites by local heating by means of irradiation of the selected bondsites through a focusable heat source of a powder layer;

removal of the powder layer not incipiently melted; and

adhesion of the at least one microcomponent to the substrate.

20. (Currently amended) The microsystem component of claim 19, characterized in that the at least one microcomponent is microcomponents (18) are smaller than 1000 μm .